Abstract of the Disclosure

A flip chip bonder comprising substrate holding means and a chip die bonder for bonding a semiconductor chip having a plurality of electrodes projecting from its front surface to a substrate held on the substrate holding means, wherein

the flip chip bonder comprises a chuck table for holding a semiconductor chip, which can be moved to a semiconductor chip take-in area, a semiconductor chip take-out area and an electrode cutting area, a cutting means having a cutting tool for cutting the plurality of electrodes projecting from the front surface of the semiconductor chip held on the chuck table and arranged in the electrode cutting area to make them uniform in height, a semiconductor chip take-in means for carrying a semiconductor chip before processing to the chuck table positioned in the semiconductor chip take-in area, and a semiconductor chip conveying means for carrying a semiconductor chip after processing held on the chuck table positioned in the semiconductor chip take-out area to the chip die bonder.